

# PCI EXPRESS™ CLOCK GENERATOR

ICS841S02I

## GENERAL DESCRIPTION



The ICS841S02I is a PLL-based clock generator specifically designed for PCI\_Express™ Clock Generation applications. This device generates a 100MHz HCSL clock. The device offers a HCSL (Host Clock Signal Level) clock output from a clock input reference of 25MHz. The input reference may be derived from an external source or by the addition of a 25MHz crystal to the on-chip crystal oscillator. An external reference may be applied to the XTAL\_IN pin with the XTAL\_OUT pin left floating.

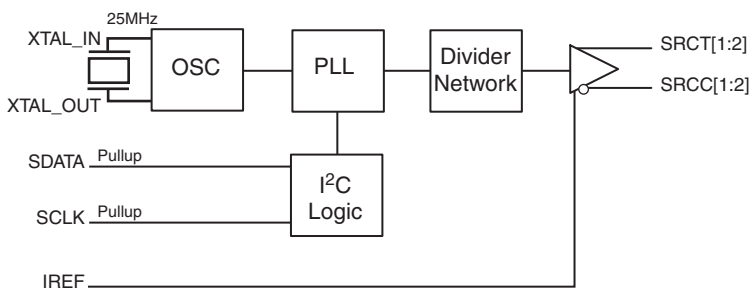
The device offers spread spectrum clock output for reduced EMI applications. An I<sup>2</sup>C bus interface is used to enable or disable spread spectrum operation as well as select either a down spread value of -0.35% or -0.5%.

The ICS841S02I is available in both standard and lead-free 20-Lead TSSOP packages.

## FEATURES

- Two 0.7V current mode differential HCSL output pairs
- Crystal oscillator interface, 25MHz
- Output frequency: 100MHz
- RMS period jitter: 3ps (maximum)
- Output skew: 35ps (maximum)
- Cycle-to-cycle jitter: 35ps (maximum)
- I<sup>2</sup>C support with readback capabilities up to 400kHz
- Spread Spectrum for electromagnetic interference (EMI) reduction
- 3.3V operating supply mode
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

## BLOCK DIAGRAM



## PIN ASSIGNMENT

VSS_SRC	1	20	VDD_SRC
VDD_SRC	2	19	SDATA
SRCT2	3	18	SCLK
SRCC2	4	17	nc
SRCT1	5	16	XTAL_OUT
SRCC1	6	15	XTAL_IN
VSS_SRC	7	14	VDD_REF
VDD_SRC	8	13	VSS_REF
VSS_SRC	9	12	VDDA
IREF	10	11	VSSA

**ICS841S02I**  
**20-Lead TSSOP**  
 6.5mm x 4.4mm x 0.92mm  
 package body  
**G Package**  
 Top View

The Preliminary Information presented herein represents a product in pre-production. The noted characteristics are based on initial product characterization and/or qualification. Integrated Device Technology, Incorporated (IDT) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 7, 9	V <sub>SS_SRC</sub>	Power		Ground for core and SRC outputs.
2, 8, 20	V <sub>DD_SRC</sub>	Power		Power supply for core and SRC outputs.
3, 4	SRCT2, SRCC2	Output		Differential output pair. HCSL interface levels.
5, 6	SRCT1, SRCC1	Output		Differential output pair. HCSL interface levels.
10	IREF	Input		A fixed precision resistor (475Ω) from this pin to ground provides a reference current used for differential current-mode SRCCx, SRCTx clock outputs.
11	V <sub>SSA</sub>	Power		Analog ground pin.
12	V <sub>DDA</sub>	Power		Power supply for PLL.
13	V <sub>SS_REF</sub>	Power		Ground for crystal interface
14	V <sub>DD_REF</sub>	Power		Power supply for crystal interface.
15, 16	XTAL_IN, XTAL_OUT	Input		Crystal oscillator interface. XTAL_IN is the input. XTAL_OUT is the output.
17	nc	Unused		No connect.
18	SCLK	Input	Pullup	SMBus compatible SCLK. This pin has an internal pullup resistor, but is in high impedance in powerdown mode. LVCMOS/LVTTL interface levels.
19	SDATA	Input/ Output	Pullup	SMBus compatible SDATA. This pin has an internal pullup resistor, but is in high impedance in powerdown mode. LVCMOS/LVTTL interface levels.

NOTE: Pullup refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
C <sub>OUT</sub>	Output Pin Capacitance		3		5	pF
L <sub>IN</sub>	Pin Inductance				7	nH

## SERIAL DATA INTERFACE

To enhance the flexibility and function of the clock synthesizer, a two-signal serial interface is provided. Through the Serial Data Interface, various device functions, such as individual clock output buffers, can be individually enabled or disabled. The registers associated with the Serial Data Interface initialize to their default setting upon power-up, and therefore, use of this interface is optional. Clock device register changes are normally made upon system initialization, if any are required. The interface cannot be used during system operation for power management functions.

## DATA PROTOCOL

The clock driver serial protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, the bytes must be accessed in sequential order from lowest to highest byte (most significant bit first) with the ability to stop after any complete byte has been transferred. For byte write and byte read operations, the system controller can access individually indexed bytes. The offset of the indexed byte is encoded in the command code, as described in *Table 3A*.

The block write and block read protocol is outlined in *Table 3B*, while *Table 3C* outlines the corresponding byte write and byte read protocol. The slave receiver address is 11010010 (D2h).

**TABLE 3A. COMMAND CODE DEFINITION**

BIT	Description
7	0 = Block read or block write operation, 1 = Byte read or byte write operation.
6:5	Chip select address, set to "00" to access device.
4:0	Byte offset for byte read or byte write operation. For block read or block write operations, these bits must be "00000".

**TABLE 3B. BLOCK READ AND BLOCK WRITE PROTOCOL**

BIT	Description = Block Write	BIT	Description = Block Read
1	Start	1	Start
2:8	Slave address - 7 bits	2:8	Slave address - 7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave
11:18	Command Code - 8 bits	11:18	Command Code - 8 bits
19	Acknowledge from slave	19	Acknowledge from slave
20:27	Byte Count - 8 bits	20	Repeat start
28	Acknowledge from slave	21:27	Slave address - 7 bits
29:36	Data byte 1 - 8 bits	28	Read = 1
37	Acknowledge from slave	29	Acknowledge from slave
38:45	Data byte 2 - 8 bits	30:37	Byte Count from slave - 8 bits
46	Acknowledge from slave	38	Acknowledge
	Data Byte/Slave Acknowledges	39:46	Data Byte 1 from slave - 8 bits
	Data Byte N - 8 bits	47	Acknowledge
	Acknowledge from slave	48:55	Data Byte 2 from slave - 8 bits
	Stop	56	Acknowledge
			Data Bytes from Slave / Acknowledges
			Data Byte N from slave - 8 bits
			Not Acknowledge

TABLE 3C. BYTE READ AND BYTE WRITE PROTOCOL

BIT	Description = Byte Write	BIT	Description = Byte Read
1	Start	1	Start
2:8	Slave address - 7 bits	2:8	Slave address - 7 bits
9	Write	9	Write
10	Acknowledge from slave	10	Acknowledge from slave
11:18	Command Code - 8 bits	11:18	Command Code - 8 bits
19	Acknowledge from slave	19	Acknowledge from slave
20:27	Data byte - 8 bits	20	Repeat start
28	Acknowledge from slave	21:27	Slave address - 7 bits
29	Stop	28	Read
		29	Acknowledge from slave
		30:37	Data from slave - 8 bits
		38	Not Acknowledge
		39	Stop

## CONTROL REGISTERS

TABLE 4A. BYTE 0:CONTROL REGISTER 0

BIT	@Pup	Name	Description
7	0	Reserved	Reserved
6	1	Reserved	Reserved
5	1	Reserved	Reserved
4	1	SRC[T/C]2	SRC[T/C]2 Output Enable 0 = Disable (Hi-Z) 1 = Enable
3	1	SRC[T/C]1	SRC[T/C]1 Output Enable 0 = Disable (Hi-Z) 1 = Enable
2	1	Reserved	Reserved
1	0	Reserved	Reserved
0	0	Reserved	Reserved

TABLE 4B. BYTE 1:CONTROL REGISTER 1

BIT	@Pup	Name	Description
7	0	Reserved	Reserved
6	0	Reserved	Reserved
5	0	Reserved	Reserved
4	0	Reserved	Reserved
3	0	Reserved	Reserved
2	0	Reserved	Reserved
1	0	Reserved	Reserved
0	0	Reserved	Reserved

TABLE 4C. BYTE 2:CONTROL REGISTER 2

BIT	@Pup	Name	Description
7	1	SRCT/C	Spread Spectrum Selection 0 = -0.35%, 1 = -0.50%
6	1	Reserved	Reserved
5	1	Reserved	Reserved
4	0	Reserved	Reserved
3	1	Reserved	Reserved
2	0	SRC	SRC Spread Spectrum Enable 0 = Spread Off, 1 = Spread On
1	1	Reserved	Reserved
0	1	Reserved	Reserved

TABLE 4D. BYTE 3:CONTROL REGISTER 3

BIT	@Pup	Name	Description
7	1	Reserved	Reserved
6	0	Reserved	Reserved
5	1	Reserved	Reserved
4	0	Reserved	Reserved
3	1	Reserved	Reserved
2	1	Reserved	Reserved
1	1	Reserved	Reserved
0	1	Reserved	Reserved

TABLE 4E. BYTE 4:CONTROL REGISTER 4

BIT	@Pup	Name	Description
7	0	Reserved	Reserved
6	0	Reserved	Reserved
5	0	Reserved	Reserved
4	0	Reserved	Reserved
3	0	Reserved	Reserved
2	0	Reserved	Reserved
1	0	Reserved	Reserved
0	1	Reserved	Reserved

TABLE 4F. BYTE 5:CONTROL REGISTER 5

BIT	@Pup	Name	Description
7	0	Reserved	Reserved
6	0	Reserved	Reserved
5	0	Reserved	Reserved
4	0	Reserved	Reserved
3	0	Reserved	Reserved
2	0	Reserved	Reserved
1	0	Reserved	Reserved
0	0	Reserved	Reserved

TABLE 4G. BYTE 6:CONTROL REGISTER 6

BIT	@Pup	Name	Description
7	0	TEST_SEL	REF/N or Hi-Z Select 0 = Hi-Z, 1 = REF/N
6	0	TEST_MODE	TEST Clock Mode Entry Control 0 = Normal Operation, 1 = REF/N or Hi-Z Mode
5	0	Reserved	Reserved
4	1	Reserved	Reserved
3	0	Reserved	Reserved
2	0	Reserved	Reserved
1	1	Reserved	Reserved
0	1	Reserved	Reserved

TABLE 4H. BYTE 7:CONTROL REGISTER 7

BIT	@Pup	Name	Description
7	0		Revision Code Bit 3
6	0		Revision Code Bit 2
5	0		Revision Code Bit 1
4	0		Revision Code Bit 0
3	0		Vendor ID Bit 3
2	0		Vendor ID Bit 2
1	0		Vendor ID Bit 1
0	1		Vendor ID Bit 0

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD\_REF} + 0.5V$
Outputs, $V_O$	-0.5V to $V_{DD\_SRC} + 0.5V$
Package Thermal Impedance, $\theta_{JA}$	73.2°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 5A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD\_REF} = V_{DDA} = V_{DD\_SRC} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD\_REF}$	Power Supply Voltage		3.135	3.3	3.465	V
$V_{DDA}$	Analog Supply Voltage		$V_{DD\_REF} - 0.25$	3.3	$V_{DD\_REF}$	V
$V_{DD\_SRC}$	Core/SRC Supply Voltage		3.135	3.3	3.465	V
$I_{DD\_REF}$	Crystal Supply Current				8	mA
$I_{DD\_SRC}$	Core/SRC Supply Current				140	mA
$I_{DDA}$	Analog Supply Current				25	mA

**TABLE 5B. DC CHARACTERISTICS,  $V_{DD\_REF} = V_{DDA} = V_{DD\_SRC} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH\text{SMBUS}}$	Input High Voltage	SDATA, SCLK	2.2			V
$V_{IL\text{SMBUS}}$	Input Low Voltage	SDATA, SCLK			1.0	V
$I_{IH}$	Input High Current	SDATA, SCLK $V_{DD} = V_{IN} = 3.465V$			5	$\mu A$
$I_{IL}$	Input Low Current	SDATA, SCLK $V_{DD} = 3.465V, V_{IN} = 0V$	-150			$\mu A$
$I_{OH}$	Output Current			14		mA
$I_{OZ}$	High Impedance Leakage Current		-10		10	$\mu A$

TABLE 6. AC CHARACTERISTICS,  $V_{DD\_REF} = V_{DDA} = V_{DD\_SRC} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
fref	Frequency			25		MHz
sclk	SCLK Frequency				400	kHz
	Frequency Tolerance; NOTE 1	XTAL			50	ppm
		External Reference			0	ppm
odc	SRCT/SRCC Duty Cycle; NOTE 2, 7		47		53	%
tsk(o)	SRCT/C to SRCT/C Clock Skew; NOTE 2, 7				35	ps
$t_{PERIOD}$	Average Period; NOTE 3		9.9970		10.0533	ns
$f_{jit(cc)}$	SRCT/C Cycle-to-Cycle Jitter; NOTE 2, 7				35	ps
$f_{jit(per)}$	Period Jitter, RMS; NOTE 2, 7				3	ps
$t_R / t_F$	SRCT/SRCC Rise/Fall Time; NOTE 4		175		700	ps
$t_{RFM}$	Rise/Fall Time Matching; NOTE 5				20	%
$t_{DC}$	XTAL_IN Duty Cycle; NOTE 6		47.5		52.5	%
$\Delta t_R / t_F$	Rise/Fall Time Variation				125	ps
$V_{HIGH}$	Voltage High		520		800	mv
$V_{LOW}$	Voltage Low		-150			mv
$V_{OX}$	Output Crossover Voltage	@ 0.7V Swing	250		550	mV
$V_{OVS}$	Maximum Overshoot Voltage				$V_{HIGH} + 0.3$	V
$V_{UDS}$	Minimum Undershoot Voltage		-0.3			V
$V_{RB}$	Ring Back Voltage				0.2	V

NOTE 1: With recommended crystal.

NOTE 2: Measured at crossing point  $V_{OX}$ .

NOTE 3: Measured at crossing point  $V_{OX}$  at 100MHz.

NOTE 4: Measured from  $V_{OL} = 0.175V$  to  $V_{OH} = 0.525V$ .

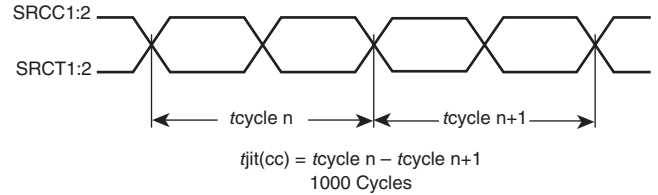
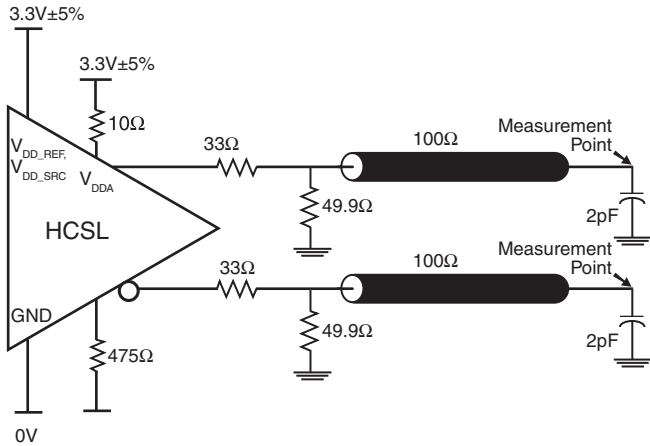
NOTE 5: Determined as a fraction of  $2 \cdot (t_R - t_F) / (t_R + t_F)$ .

NOTE 6: The device will operate reliably with input duty cycles up to 30/70% but the REF clock duty cycle will not be within specification

NOTE 7: Measured using a 50Ω to GND termination.

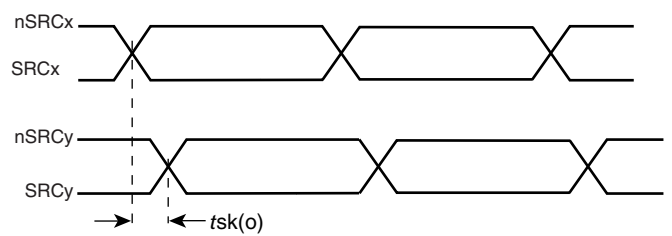
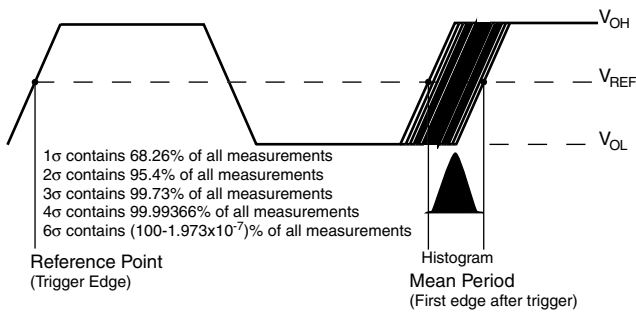


## PARAMETER MEASUREMENT INFORMATION



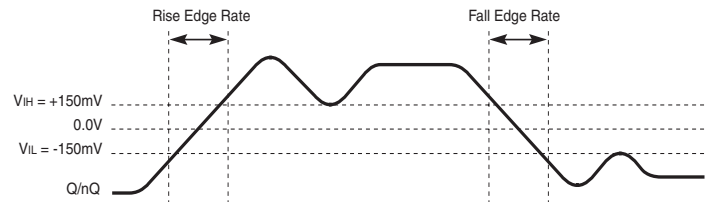
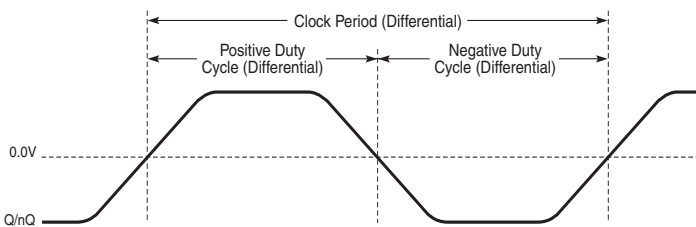
3.3V HCSL OUTPUT LOAD AC TEST CIRCUIT

CYCLE-TO-CYCLE JITTER



RMS PERIOD JITTER

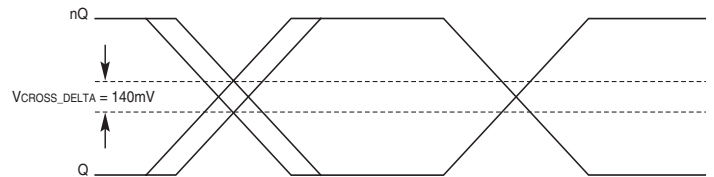
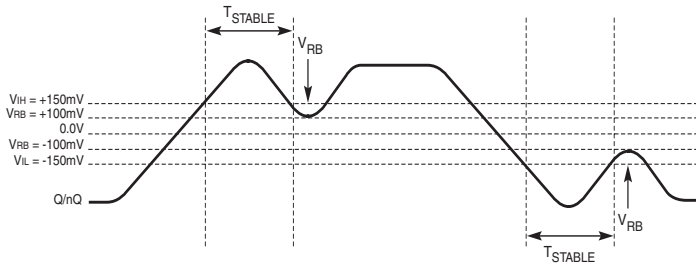
OUTPUT SKEW



DIFFERENTIAL MEASUREMENT POINTS FOR DUTY CYCLE/PERIOD

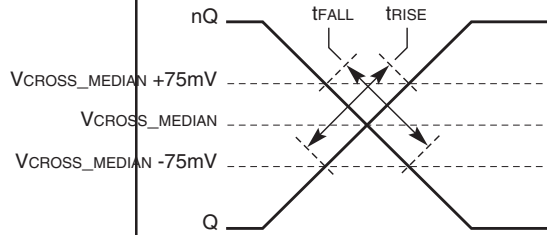
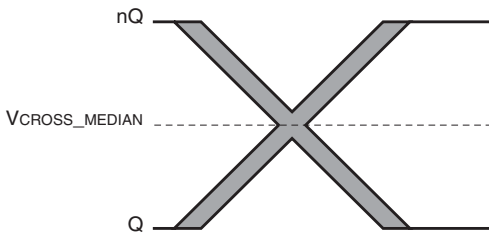
DIFFERENTIAL MEASUREMENT POINTS FOR RISE/FALL TIME

## PARAMETER MEASUREMENT INFORMATION, CONTINUED

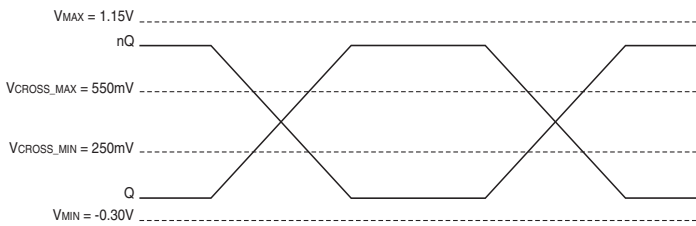


### DIFFERENTIAL MEASUREMENT POINTS FOR RINGBACK

### SE MEASUREMENT POINTS FOR DELTA CROSS POINT



### SE MEASUREMENT POINTS FOR RISE/FALL TIME MATCHING



### SE MEASUREMENT POINTS FOR ABSOLUTE CROSS POINT/SWING

## APPLICATION INFORMATION

### POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The ICS841S02I provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{DD\_SRC}$ ,  $V_{DDA}$  and  $V_{DD\_REF}$  should be individually connected to the power supply plane through vias, and  $0.01\mu\text{F}$  bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic  $V_{DD\_SRC}$  pin and also shows that  $V_{DDA}$  requires that an additional  $10\Omega$  resistor along with a  $10\mu\text{F}$  bypass capacitor be connected to the  $V_{DDA}$  pin.

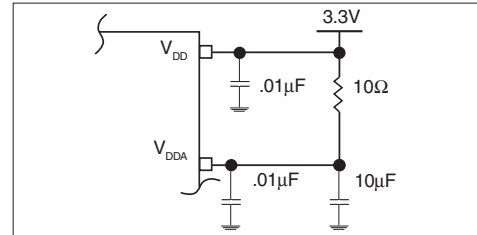


FIGURE 1. POWER SUPPLY FILTERING

### USING THE ON-BOARD CRYSTAL OSCILLATOR

The ICS841S02I features a fully integrated Pierce oscillator to minimize system implementation costs. The recommended operation of the ICS841S02I is with a 25MHz, 18pF parallel resonant crystal. See *Table 7* for complete crystal specifications.

For proper operation, a minimum of 10pF capacitance on each crystal pin is required. The capacitor values shown in *Figure 2*

are typical values for the recommended crystal as show in *Table 7*. The specific values may be adjusted to trim the frequency for the individual board layouts if desired.

The crystal and optional trim capacitors should be located as close to the ICS841S02I XTAL\_IN and XTAL\_OUT pins as possible to minimize board level parasitics.

TABLE 7. RECOMMENDED CRYSTAL SPECIFICATIONS

Parameter	Value
Crystal Cut	Fundamental AT Cut
Resonance	Parallel Resonance
Shunt Capacitance ( $C_L$ )	5-7pF
Load Capacitance ( $C_O$ )	18pF
Equivalent Series Resistance (ESR)	20-50Ω

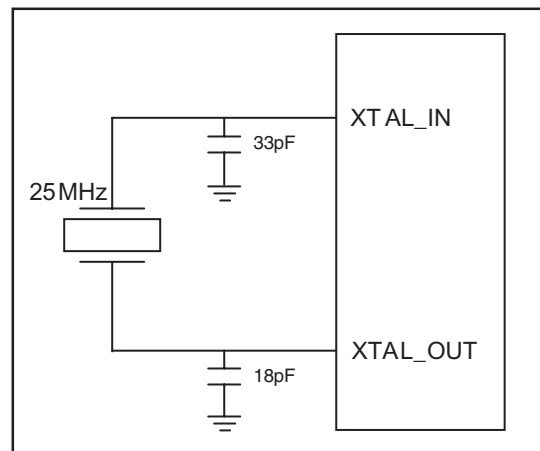


FIGURE 2. CRYSTAL OSCILLATOR WITH TRIM CAPACITOR

## RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

### INPUTS:

#### LVC MOS CONTROL PINS

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

### OUTPUTS:

#### HCSL OUTPUTS

All unused HCSL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

## OUTPUT DRIVER CURRENT

The ICS841S02I outputs are HCSL current drive with the current being set with a resistor from  $I_{REF}$  to ground. For a 50Ω pc board trace, the drive current would typically be set with a  $R_{REF}$  of 475Ω which products an  $I_{REF}$  of 2.32mA. The  $I_{REF}$  is multiplied by a current mirror to an output drive of 6\*2.32mA or 13.92mA. See *Figure 3* for current mirror and output drive details.

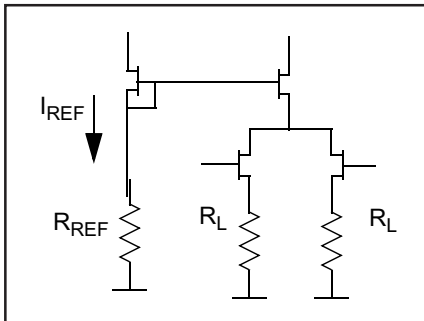
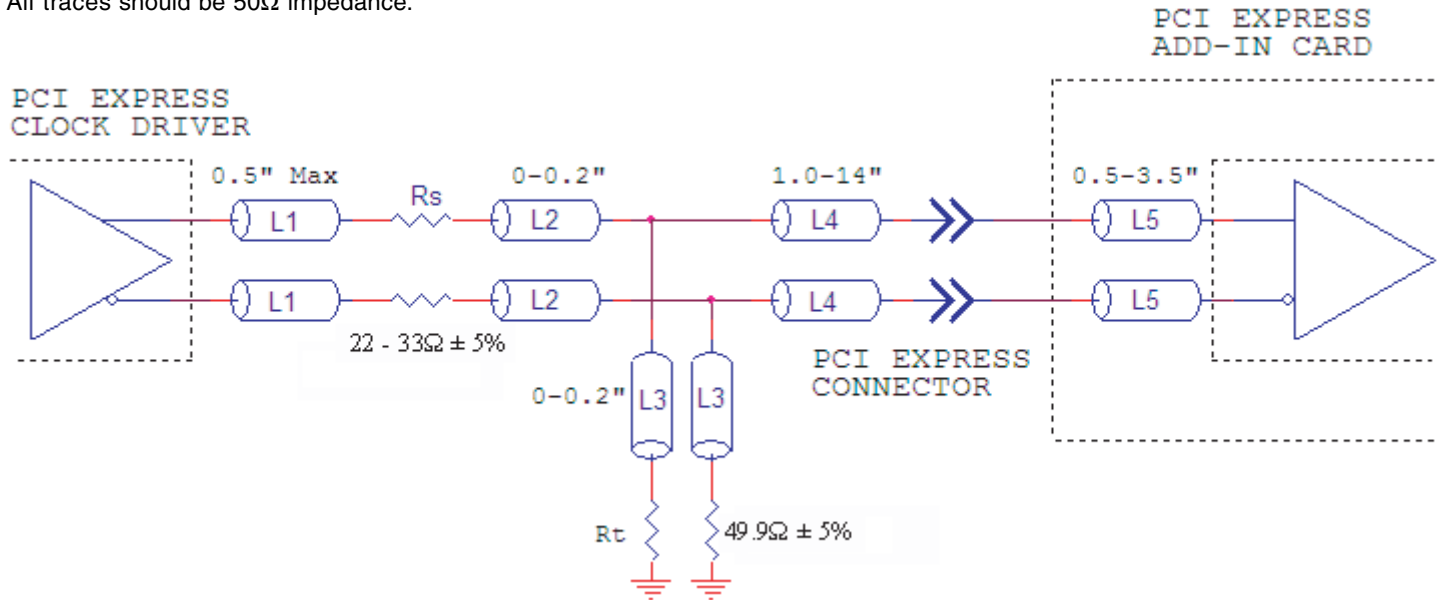


FIGURE 3. HCSL CURRENT MIRROR AND OUTPUT DRIVE

**RECOMMENDED TERMINATION**

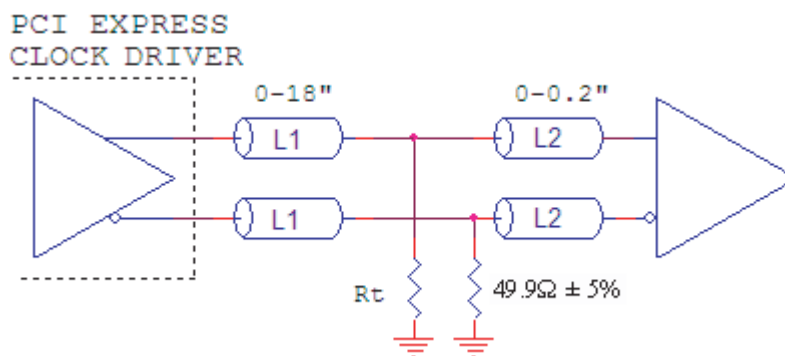
Figure 4A is the recommended termination for applications which require the receiver and driver to be on a separate PCB. All traces should be 50Ω impedance.



**FIGURE 4A. RECOMMENDED TERMINATION**

Figure 4B is the recommended termination for applications which require a point to point connection and contain the driver

and receiver on the same PCB. All traces should all be 50Ω impedance.



**FIGURE 4B. RECOMMENDED TERMINATION**

## RELIABILITY INFORMATION

TABLE 8.  $\theta_{JA}$  vs. AIR FLOW TABLE FOR 20 LEAD TSSOP

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### TRANSISTOR COUNT

The transistor count for ICS841S02I is: 1874

PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

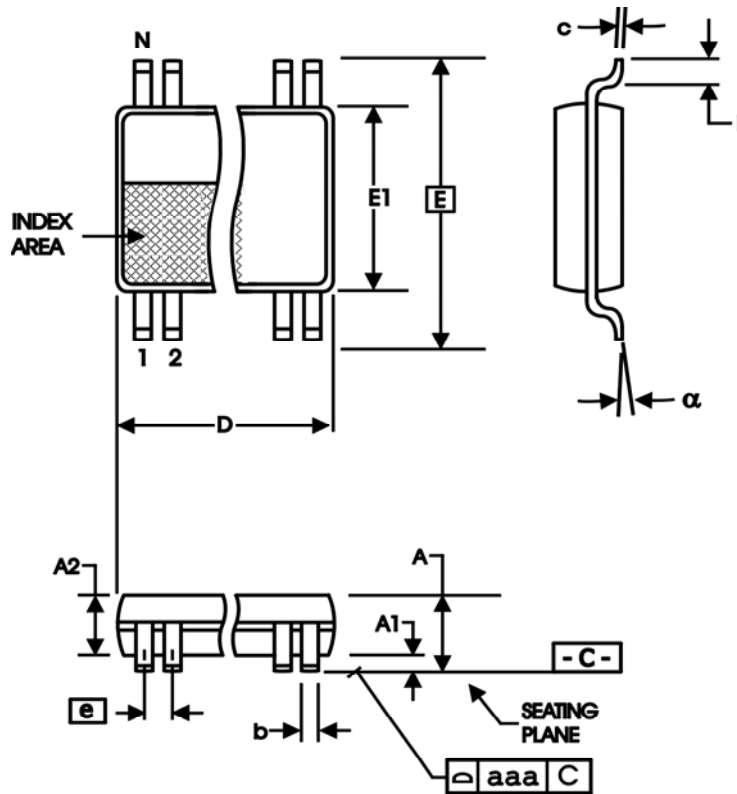


TABLE 9. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MIN	MAX
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

TABLE 10. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS841S02BGI	ICS841S02BGI	20 Lead TSSOP	tube	-40°C to 85°C
ICS841S02BGIT	ICS841S02BGI	20 Lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS841S02BGILF	ICS841S02BIL	20 Lead "Lead-Free" TSSOP	tube	-40°C to 85°C
ICS841S02BGILFT	ICS841S02BIL	20 Lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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